IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composi © Copyright 2005. IPC, international and Pan-Ai	Bannockb	urn, Illinois. A	ll rights reserved ur	Thi leve	is docume el parts, tl	ent is a decla the declaration	ration on enco	of the subs ompasses al	tances v ll lower	vithin the mar level material	ufacture ls for wh	er listed it nich the m	em. Nanufac	ote: if the	e item is an as s engineering	sembly with lo responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Materia	ials and Mfg Information				
Supplier Informa	ntion																
Company name*	Company unique ID			Unique ID Authority						Response Date*							
onsemi													2024-04-25				
Contact Name			Title - Contact]	Phone - Contact*						Email - Contact*				
Product-Env-Stewar	Product Enviro Compliance				NA						Product-Env-Stewards@onsemi.com						
Authorized Representative* Tit				Title - Representative			Phone - Representative*						Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA						Product-Env-Stewards@onsemi.com					
Requester	Requester Item Number Mfr Iter		Number			Effective D	ate	Version	Manufacturing Site		Site	V	Weight*		UOM	Unit Type	
		NCV8160BMX330TB XDFN4 HZ 3 G Noise and High		XDFN4 HZ 3.3V I Noise and High PS	LDO 250 mA, Ultr SRR	ra-Low	2024-04-25 T		ТНВ		1	.434		mg	Each		
Manufacturing P	roccess Information	n															
Terminal P	Terminal Plating / Grid Array Material		Terminal Base Alloy J-S		-STD-020 MSL Ra	D-020 MSL Rating		Peak Process Body Temperatu		perature	nre Max Time at Peak Temper		Temperatu	ire N	Number o	of Reflow Cyc	les
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		u) (no	CU Alloy 1				260		С		30 seco		second	ls 3	3		
Comments				•			•		•				•	•			
evel 1 - maximum tin	ne at peak temperature	during sol	dering is 10-3	0 seconds													
For more information	n regarding material con	nposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Die Attach	0.13	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.0416	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0884	mg
Lead Frame	0.58	mg	Supplier	Tin (Sn)	7440-31-5		0.0014	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0013	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0014	mg
			Supplier	Copper (Cu)	7440-50-8		0.5758	mg
Mold Compound-Black	0.6	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.048	mg
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.012	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.519	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.018	mg
Plating	0.004	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.0035	mg
			Supplier	Gold (Au)	7440-57-5		0.0004	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg